



Semiconductor Device Type: (NYA) 024 VQFN 4x4x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4	
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	22.72	(mg) Total	Mold Compound	% of Total Weight	53.84
Fused Silica	60676-86-0	Mold Compound	48.187	20.335	481,868		Fused Silica	60676-86-0	89.50	
Epoxy Resin	Trade Secret	Mold Compound	2.692	1.136	26,920		Epoxy Resin	Trade Secret	5.00	
Phenol Resin	Trade Secret	Mold Compound	2.154	0.909	21,536		Phenol Resin	Trade Secret	4.00	
Aromatic Phosphate	Trade Secret	Mold Compound	0.700	0.295	6,999		Aromatic Phosphate	Trade Secret	1.30	
Carbon Black	1333-86-4	Mold Compound	0.108	0.045	1,077		Carbon Black	1333-86-4	0.20	
Copper	7440-50-8	Lead Frame	40.302	17.007	403,017		Total			
Iron	7439-89-6	Lead Frame	0.953	0.402	9,527	17.48	(mg) Total	Lead Frame	% of Total Weight	41.42
Phosphorous	7723-14-0	Lead Frame	0.104	0.044	1,036		Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-6	Lead Frame	0.062	0.026	621		Iron	7439-89-6	2.30	
Silver	7440-22-4	Die Attach	0.100	0.042	1,001		Phosphorous	7723-14-0	0.25	
Acrylic Resin	Trade secret	Die Attach	0.018	0.008	182		Zinc (Metal)	7440-66-6	0.15	
Epoxy Resin	Trade secret	Die Attach	0.012	0.005	117	Total			100.00	0.13
Silicon	7440-21-3	Chip (Die)	1.660	0.701	16,600	0.05	(mg) Total	Die Attach	% of Total Weight	
Gold	7440-57-5	Wire Bond	0.520	0.219	5,200		Silver	7440-22-4	77.00	
Nickel	7440-02-0	Plating on external leads (pins)	2.368	0.999	23,678		Acrylic Resin	Trade secret	14.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.050	0.021	501		Epoxy Resin	Trade secret	9.00	
Gold	7440-57-5	Plating on external leads (pins)	0.012	0.005	122	Total			100.00	1.66
TOTALS:			100.000	42.200	1,000,000	0.70	Total (mg)	Chip (Die)	% of Total Weight	
0.0422 g Total Mass							Doped Silicon	7440-21-3	100.00	
							Total			
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)										
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and for analytical test data.										
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.										
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/										
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.										
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table										
						42.20				100.00

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